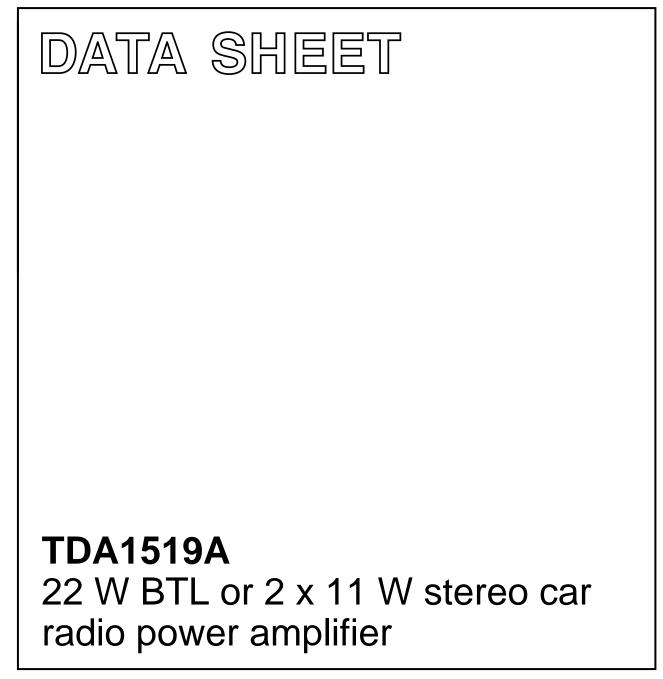
INTEGRATED CIRCUITS



Product specification File under Integrated Circuits, IC01 May 1992



GENERAL DESCRIPTION

The TDA1519A is an integrated class-B dual output amplifier in a 9-lead single in-line (SIL) plastic power package. The device is primarily developed for car radio applications.

Features

- · Requires very few external components for Bridge Tied Load (BTL)
- Stereo or BTL application
- High output power
- Low offset voltage at output (important for BTL)
- Fixed gain

- · Good ripple rejection
- · Mute/stand-by switch
- · Load dump protection
- AC and DC short-circuit-safe to ground and V_P

- Thermally protected
- · Reverse polarity safe
- Capability to handle high energy on outputs (V_P = 0 V)
- No switch-on/switch-off plop
- · Protected against electrostatic discharge
- Low thermal resistance
- · Identical inputs (inverting and non-inverting)
- Compatible with TDA1519B (except output power).

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.
Supply voltage range					
operating		VP	6.0	14.4	17.5
non-operating		VP	-	-	30
load dump protected		VP	-	-	45
Repetitive peak output current		I _{ORM}	-	-	4
Total quiescent current		I _{tot}	-	40	80
Stand-by current		I _{sb}	-	0.1	100
Switch-on current		l _{sw}	-	-	40
Input impedance					
BTL		Z _I	25	-	-
stereo		Z _I	50	-	-
Stereo application					
Output power	THD = 10%; 4 Ω	Po	_	6	_
	THD = 10%; 2 Ω	Po	_	11	_
Channel separation		α	40	-	_
Noise output voltage		V _{no(rms)}	-	150	_

QUICK REFERENCE DATA

TDA1519A

UNIT

V V V А

mΑ

μΑ

μΑ

kΩ kΩ

W W

dB μV

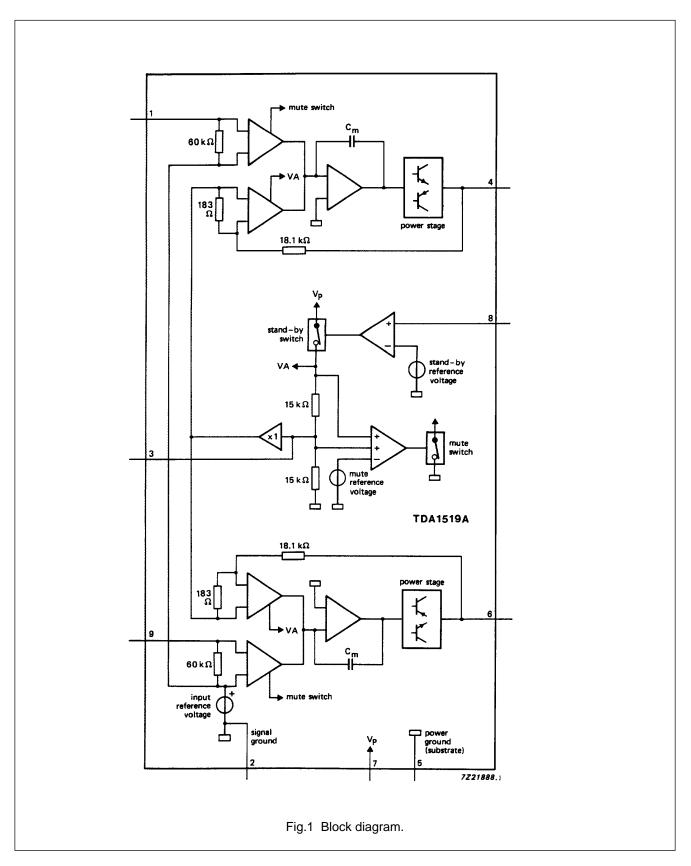
TDA1519A

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
BTL application						
Output power	THD = 10%; 4 Ω	Po	_	22	_	W
Supply voltage ripple rejection	$R_{S} = 0 \Omega$					
	f = 100 Hz	RR	34	_	_	dB
	f = 1 kHz to 10 kHz	RR	48	-	_	dB
DC output offset voltage		ΔV ₀	_	-	250	mV
Crystal temperature		T _c	_	-	150	°C

PACKAGE OUTLINES

9 lead SIL; plastic power (SOT131); SOT131-2; 1996 July 22.

9-lead SIL-bent-to-DIL; plastic power (SOT157); SOT157-2; 1996 July 22.



PINNING

1	NINV	non-inverting input
2	GND1	ground (signal)
3	RR	supply voltage ripple rejection
4	OUT1	output 1
5	GND2	ground (substrate)
6	OUT2	output 2
7	V _P	positive supply voltage
8	M/SS	mute/stand-by switch
9	INV	inverting input

FUNCTIONAL DESCRIPTION

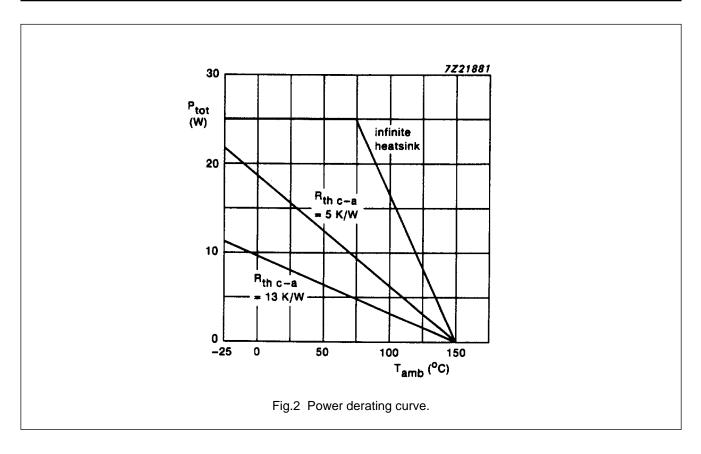
The TDA1519A contains two identical amplifiers with differential input stages. The gain of each amplifier is fixed at 40 dB. A special feature of this device is the mute/stand-by switch which has the following features:

- Low stand-by current (< 100 μA)
- Low mute/stand-by switching current (low cost supply switch)
- Mute condition.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

PARAMETER	CONDITIONS	SYMBOL	MIN.	MAX.	UNIT
Supply voltage					
operating		V _P	_	17.5	V
non-operating		V _P	-	30	V
load dump protected	during 50 ms; $t_r \ge 2.5$ ms	V _P	-	45	V
AC and DC short-circuit-safe voltage		V _{PSC}	_	18	V
Reverse polarity		V _{PR}	_	6	V
Energy handling capability at outputs	$V_{P} = 0 V$		_	200	mJ
Non-repetitive peak output current		I _{OSM}	_	6	A
Repetitive peak output current		I _{ORM}	-	4	А
Total power dissipation	see Fig.2	P _{tot}	-	25	W
Crystal temperature		T _c	-	150	°C
Storage temperature range		T _{stg}	-55	+ 150	°C



DC CHARACTERISTICS

V_P = 14.4 V; T_{amb} = 25 °C; measurements taken using Fig.3; unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply						
Supply voltage range	note 1	VP	6.0	14.4	17.5	v
Total quiescent current		I _{tot}	-	40	80	mA
DC output voltage	note 2	Vo	-	6.95	-	V
DC output offset voltage		ΔV ₄₋₆	-	_	250	mV
Mute/stand-by switch						
Switch-on voltage level		V _{ON}	8.5	_	_	V
Mute condition		V _{mute}	3.3	-	6.4	V
Output signal in mute position	V _I = 1 V (max.);					
	f = 20 Hz to					
	15 kHz	Vo	-	-	20	mV
DC output offset voltage		ΔV ₄₋₆	-	_	250	mV

TDA1519A

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Stand-by condition		V _{sb}	0	-	2	V
DC current in stand-by condition		I _{sb}	-	_	100	μA
Switch-on current		I _{sw}	-	12	40	μA

AC CHARACTERISTICS

 $V_P = 14.4 \text{ V}$; $R_L = 4 \Omega$; f = 1 kHz; $T_{amb} = 25 \text{ °C}$; measurements taken using Fig.3; unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Stereo application						
Output power	note 3					
	THD = 0.5%	Po	4	5	_	w
	THD = 10%	Po	5.5	6.0	_	w
Output power at $R_L = 2 \Omega$	note 3					
	THD = 0.5%	Po	7.5	8.5	_	w
	THD = 10%	Po	10	11	_	w
Total harmonic distortion	P _o = 1 W	THD	_	0.1	_	%
Low frequency roll-off	note 4					
	–3 dB	fL	_	45	_	Hz
High frequency roll-off	–1 dB	f _H	20	_	_	kHz
Closed loop voltage gain		G _v	39	40	41	dB
Supply voltage ripple rejection						
ON	notes 5 and 6	RR	40	-	_	dB
ON	notes 5 and 7	RR	45	-	_	dB
mute	notes 5 and 8	RR	45	-	_	dB
stand-by	notes 5 and 8	RR	80	-	_	dB
Input impedance		Z _i	50	60	75	kΩ
Noise output voltage						
(RMS value)	note 9					
ON	$R_{S} = 0 \Omega$	V _{no(rms)}	-	150	_	μV
ON	$R_S = 10 \ k\Omega$	V _{no(rms)}	-	250	500	μV
mute	note 10	V _{no(rms)}	-	120	_	μV
Channel separation	$R_{S} = 10 \text{ k}\Omega$	α	40	-	_	dB
Channel unbalance		∆G _v	_	0.1	1	dB

TDA1519A

AC CHARACTERISTICS

 $V_P = 14.4 \text{ V}$; $R_L = 4 \Omega$; f = 1 kHz; $T_{amb} = 25 \text{ °C}$; measurements taken using Fig.4; unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
BTL application						
Output power	note 3					
	THD = 0.5%	Po	15	17	_	w
	THD = 10%	Po	20	22	_	w
Output power at V _P = 13.2 V	note 3					
	THD = 0.5%	Po	_	13	_	w
	THD = 10%	Po	_	17.5	-	W
Total harmonic distortion	$P_0 = 1 W$	THD	-	0.1	_	%
Power bandwidth	THD = 0.5%;					
	$P_o = -1 dB;$			35 to		
	w.r.t. 15 W	Bw	_	15 000	_	Hz
Low frequency roll-off	note 4					
	-1 dB	fL	_	45	_	Hz
High frequency roll-off	-1 dB	f _H	20	_	_	kHz
Closed loop voltage gain		G _v	45	46	47	dB
Supply voltage ripple rejection						
ON	notes 5 and 6	RR	34	_	_	dB
ON	notes 5 and 7	RR	48	_	_	dB
mute	notes 5 and 8	RR	48	_	_	dB
stand-by	notes 5 and 8	RR	80	-	-	dB
Input impedance		Z _i	25	30	38	kΩ
Noise output voltage						
(RMS value)	note 9					
ON	R _S = 0 Ω	V _{no(rms)}	_	200	_	μV
ON	R _S = 10 kΩ	V _{no(rms)}	_	350	700	μV
mute	note 10	V _{no(rms)}	-	180	-	μV

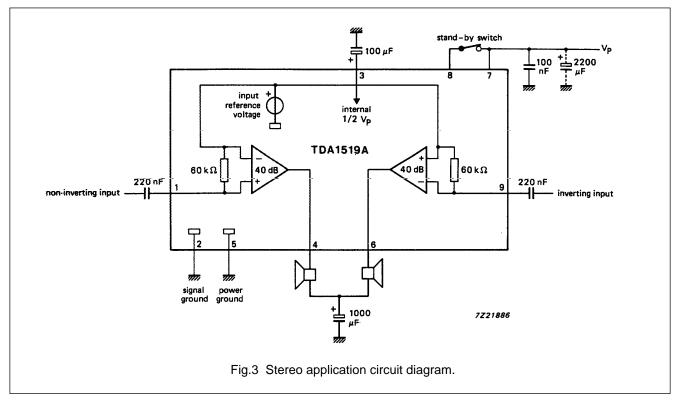
Notes to the characteristics

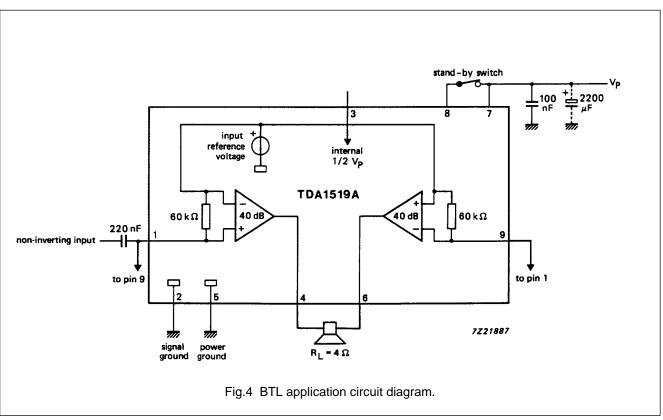
1. The circuit is DC adjusted at V_P = 6 V to 17.5 V and AC operating at V_P = 8.5 V to 17.5 V.

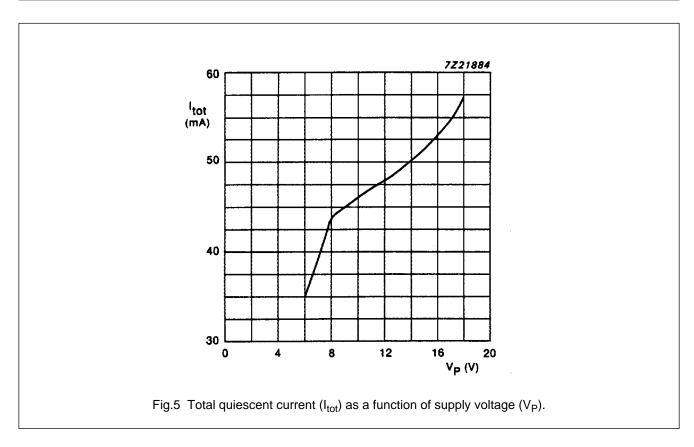
- 2. At 17.5 V < V_P < 30 V the DC output voltage \leq V_P/2.
- 3. Output power is measured directly at the output pins of the IC.
- 4. Frequency response externally fixed.
- 5. Ripple rejection measured at the output with a source impedance of 0 Ω (maximum ripple amplitude of 2 V).
- 6. Frequency f = 100 Hz.
- 7. Frequency between 1 kHz and 10 kHz.
- 8. Frequency between 100 Hz and 10 kHz.
- 9. Noise voltage measured in a bandwidth of 20 Hz to 20 kHz.
- 10. Noise output voltage independent of R_S (V_I = 0 V).

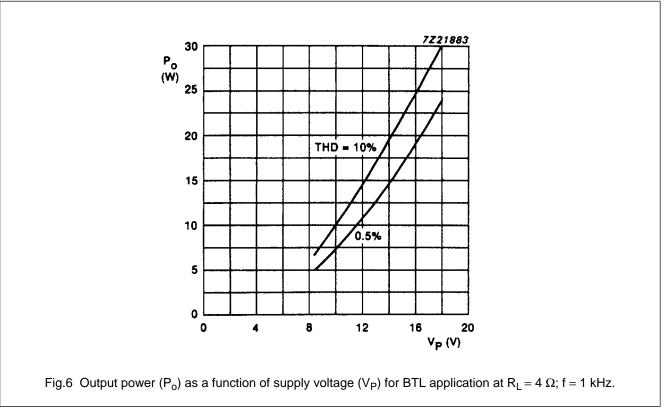
TDA1519A

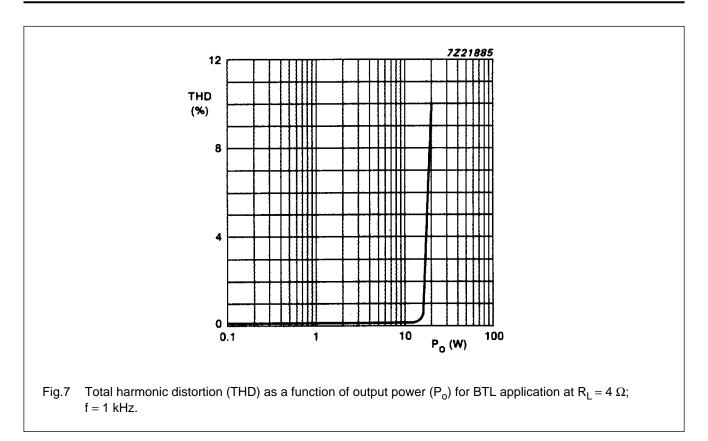
APPLICATION INFORMATION

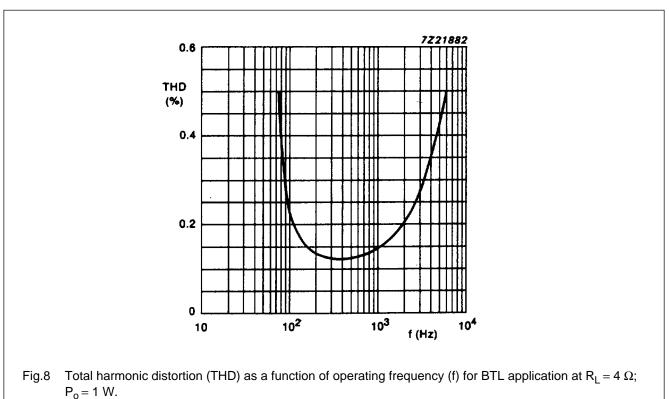










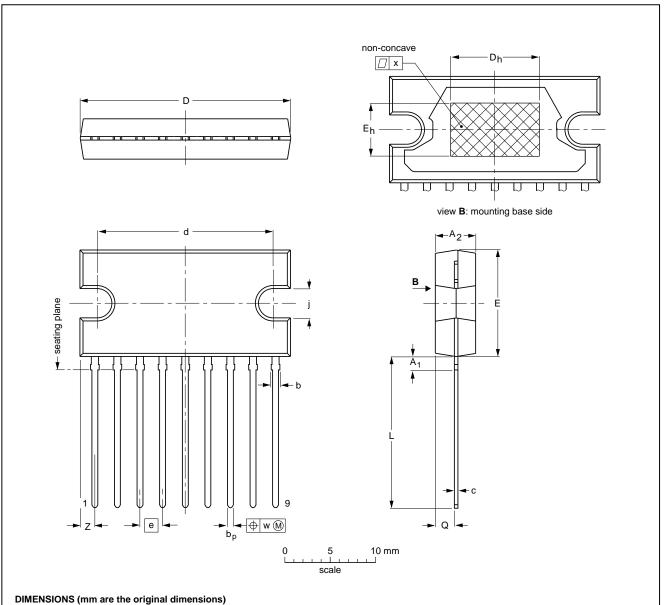


TDA1519A

22 W BTL or 2 x 11 W stereo car radio power amplifier

PACKAGE OUTLINES

SIL9P: plastic single in-line power package; 9 leads

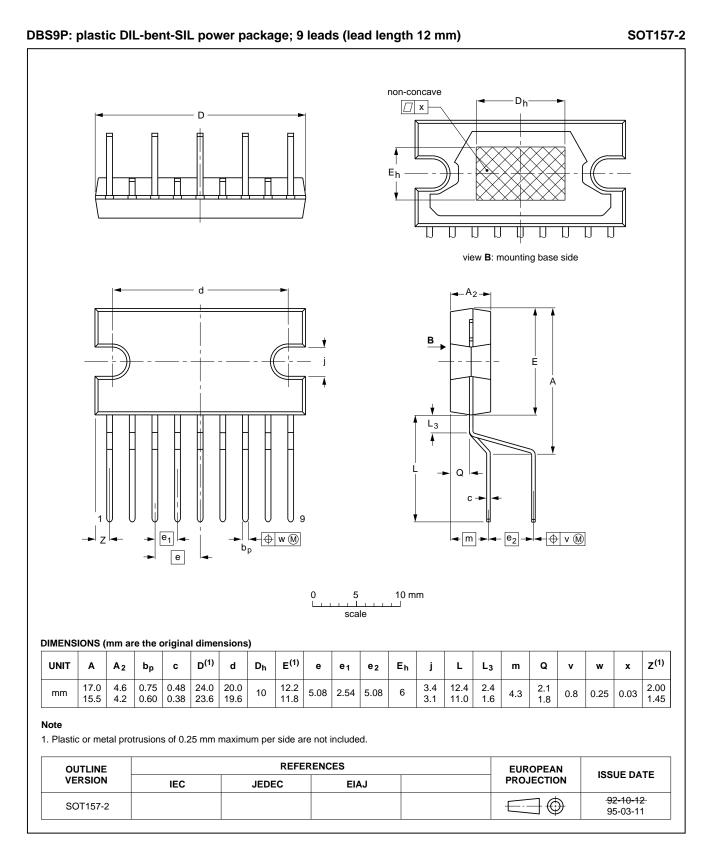


UNIT	A ₁ max.	A ₂	b max.	bp	с	D ⁽¹⁾	d	D _h	E ⁽¹⁾	е	E _h	j	L	Q	w	x	Z ⁽¹⁾
mm	2.0	4.6 4.2	1.1	0.75 0.60	0.48 0.38	24.0 23.6	20.0 19.6	10	12.2 11.8	2.54	6	3.4 3.1	17.2 16.5	2.1 1.8	0.25	0.03	2.00 1.45

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ	PROJECTION			
SOT131-2					-92-11-17 95-03-11		



SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					
more of the limiting values r of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or nay cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification imiting values for extended periods may affect device reliability.				
Application information					
Where application information is given, it is advisory and does not form part of the specification.					

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.